

Vishay Siliconix

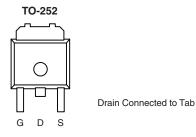
# N-Channel 100-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω)	I <sub>D</sub> (A)		
100	0.025 at V <sub>GS</sub> = 10 V	40		
100	0.028 at V <sub>GS</sub> = 4.5 V	38		

#### FEATURES

- TrenchFET<sup>®</sup> Power MOSFET
- 175 °C Maximum Junction Temperature
- 100 % Rg Tested





Top View

Ordering Information: SUD40N10-25 SUD40N10-25-E3 (Lead (Pb)-free)

N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	100	N			
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
	T <sub>C</sub> = 25 °C	1	40	-		
Continuous Drain Current $(T_J = 175 \ ^{\circ}C)^{b}$	T <sub>C</sub> = 125 °C	I <sub>D</sub>	23			
Pulsed Drain Current	I <sub>DM</sub>	70	А			
Continuous Source Current (Diode Conduction)		۱ <sub>S</sub>	40			
Avalanche Current	I <sub>AS</sub>	40				
Single Pulse Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	80	mJ		
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136 <sup>b</sup>	w		
	T <sub>A</sub> = 25 °C	۲D	3 <sup>a</sup>	VV		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
hunding to Ambigut	t ≤ 10 s	R <sub>thJA</sub>	15	18	°C/W		
Junction-to-Ambient <sup>a</sup>	Steady State		40	50			
Junction-to-Case		R <sub>thJC</sub>	0.85	1.1			

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

\* Pb containing terminations are not RoHS compliant, exemptions may apply.

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Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static		· · · · · · · · · · · · · · · · · · ·					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	100			v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.0		3.0	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50	ο μΑ	
		$V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_{J}$ = 175 °C			250	-	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	70			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 40 A		0.02	0.025		
	Б	$V_{GS}$ = 10 V, I <sub>D</sub> = 40 A, T <sub>J</sub> = 125 °C	0.05		0.05		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS}$ = 10 V, I <sub>D</sub> = 40 A, T <sub>J</sub> = 175 °C			0.063	Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A		0.022	0.028		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 40 A		70		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			2400		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V, V_{DS} = 25 V, F = 1 MHz$		290			
Reverse Transfer Capacitance	C <sub>rss</sub>			120			
Total Gate Charge <sup>c</sup>	Qg			40	60		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 40 \text{ A}$		11		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			9			
Gate Resistance	R <sub>g</sub>		1		3.5	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	13		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 1.25 $\Omega$		40	60		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 40 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_g$ = 2.5 $\Omega$		15	25	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			80	120		
Source-Drain Diode Ratings and Cha	racteristics 7	Γ <sub>C</sub> = 25 °C		·	· · · · · ·		
Pulsed Current	I <sub>SM</sub>				70	А	
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 40 A, dl/dt = 100 A/μs		75	120	ns	

Notes:

a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

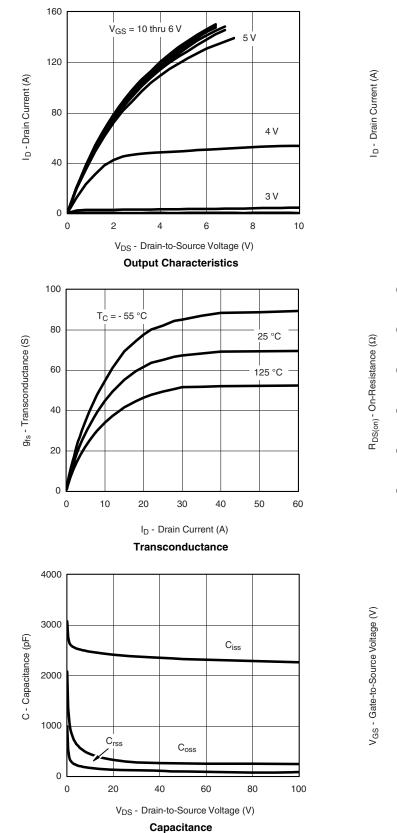
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

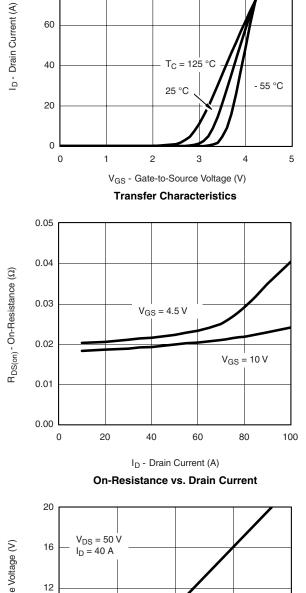


# SUD40N10-25

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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



100

80

8

4

0

0

20

40

Qg - Total Gate Charge (nC)

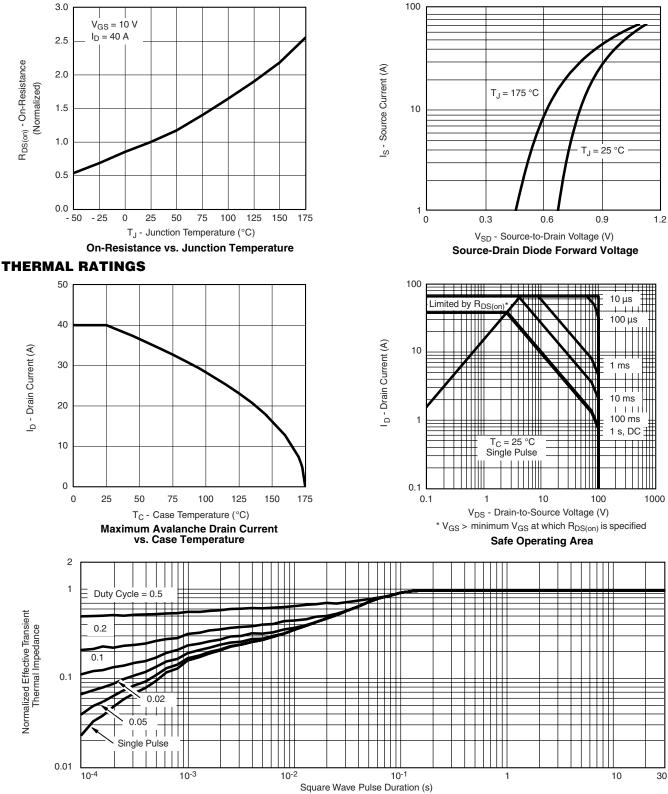
Gate Charge

80

60

### **Vishay Siliconix**

### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



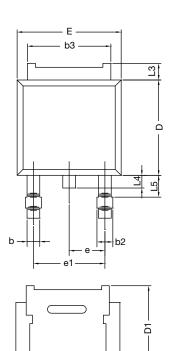
Normalized Thermal Transient Impedance, Junction-to-Case

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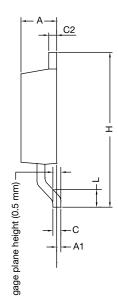
/ISHA







E1



**TO-252AA** Case Outline

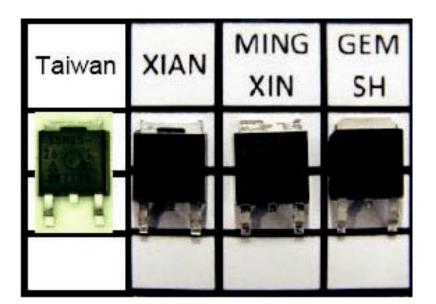
	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T13- DWG: 534	0359-Rev. O, 7	03-Jun-13	I		

### Notes

Notes

• Dimension L3 is for reference only.

• Xi'an, Mingxin, and GEM SH actual photo.



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### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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